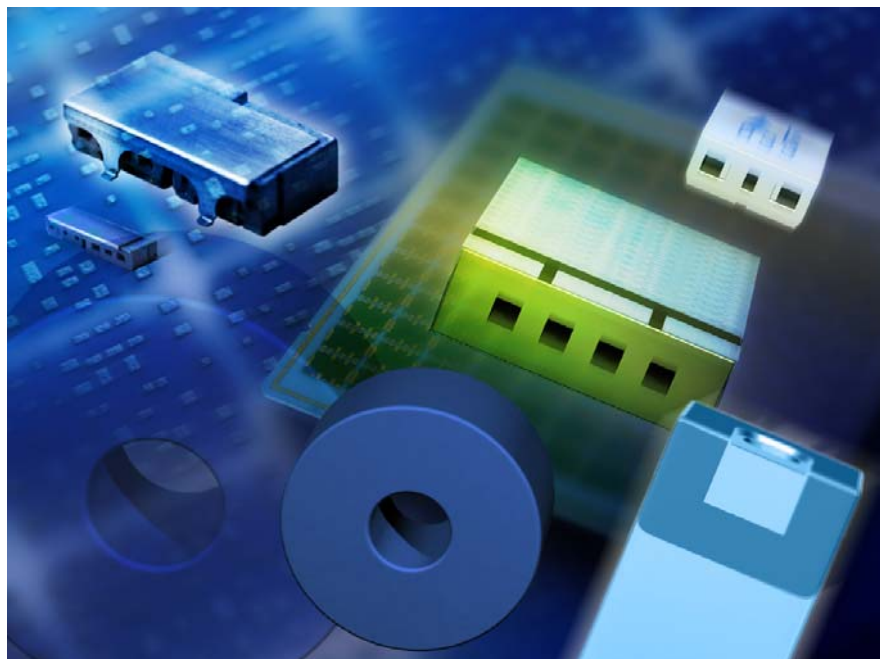


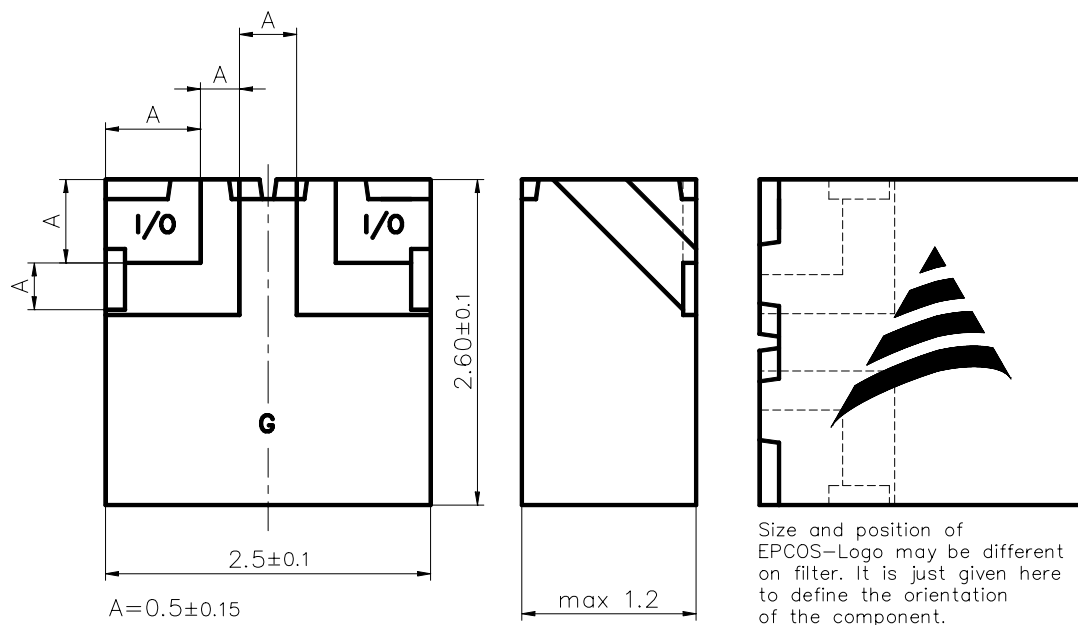
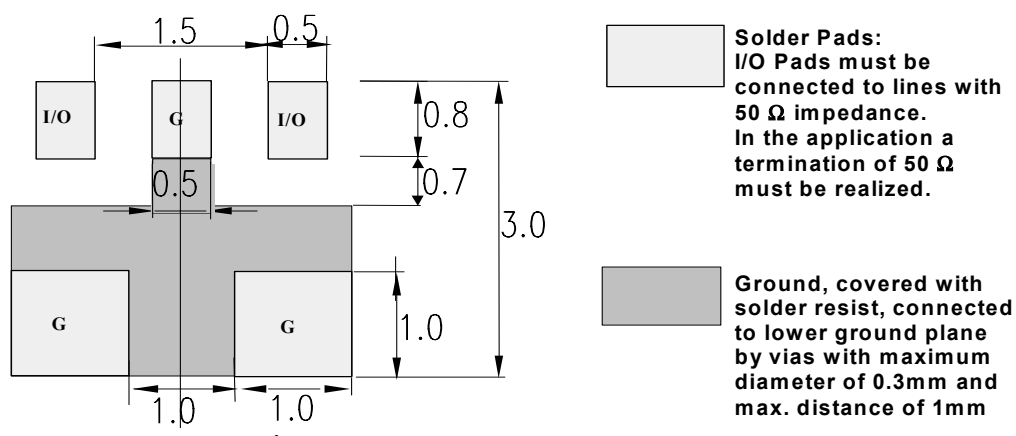
Preliminary Datasheet

Features

- Low Profile (maximum height 1.2 mm)
- SMD filter consisting of coupled resonators with stepped impedances
- Low losses
- High attenuations at GSM (900, 1800, 1900) and UMTS bands
- High attenuation at 2 times center frequency
- Excellent reflow solderability, no migration effect due to copper/tin metallization

Index

- Page 2
 - Dimension Limits , Marking
 - Recommended footprint
- Page 3
 - Characteristics
 - Maximum ratings
 - Typical passband characteristic
- Page 4
 - Processing information
 - Soldering requirements
 - Delivery mode

ISSUE DATE	20.05.03	ISSUE	P1	PUBLISHER	SAW MWC PD F	PAGE	1/4
------------	----------	-------	----	-----------	--------------	------	-----

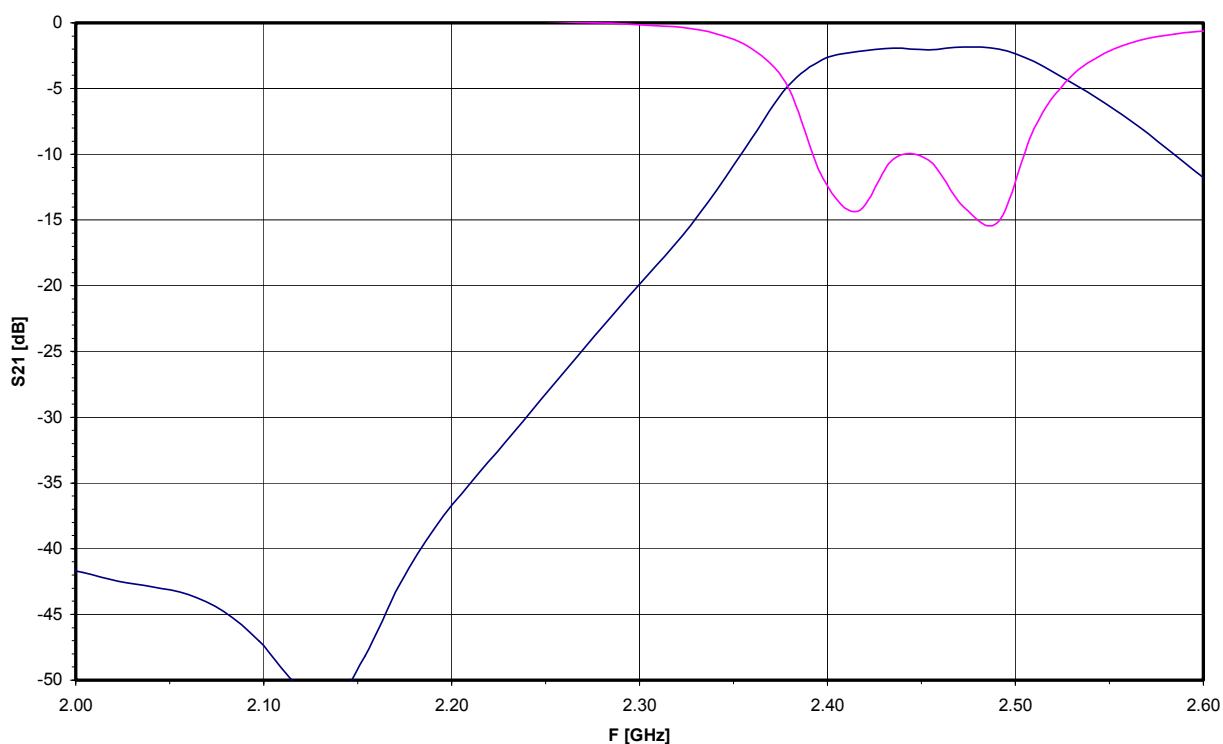
Preliminary Datasheet
Dimension Limits , Marking

Recommended footprint (Same Footprint as for „X“101 and „X“201 Wlan-Series)


Preliminary Datasheet

Characteristics (over whole temperature range)		min.	typ.	max.	
Center frequency	f_c	-	2.450	-	GHz
Insertion loss in Passband	α_{IL}		2.2	2.5	dB
Passband (2400- 2500)	B	100			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.5	0.8	dB
Return Loss in dB / Standing wave ratio			-11 / 1.8	-9.5 / 2.0	
Impedance	Z		50		Ω
Attenuation	α				
	at DC to 1580 MHz	40	43		dB
	at 1805 to 1990 MHz	38	41		dB
	at 2110 to 2170 MHz	35	37		dB
	at 3200 to 4600 MHz	20	25		dB
	at 4800 to 5000 MHz	25	30		dB
RF input power (2400 – 2500 MHz)				30	dBm

Maximum ratings

IEC climatic category (IEC 68-1)		- 40 / + 90/56	
Operating temperature	T_{op}	- 40 / + 85	°C

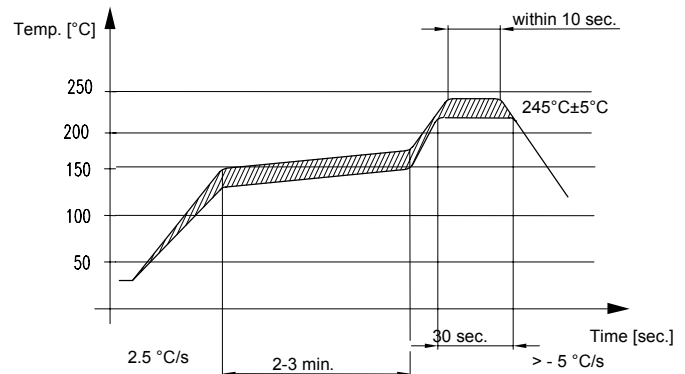
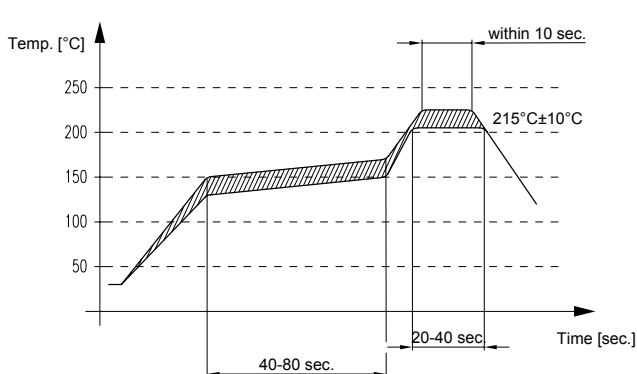
Typical passband characteristics


Preliminary Datasheet
Processing information

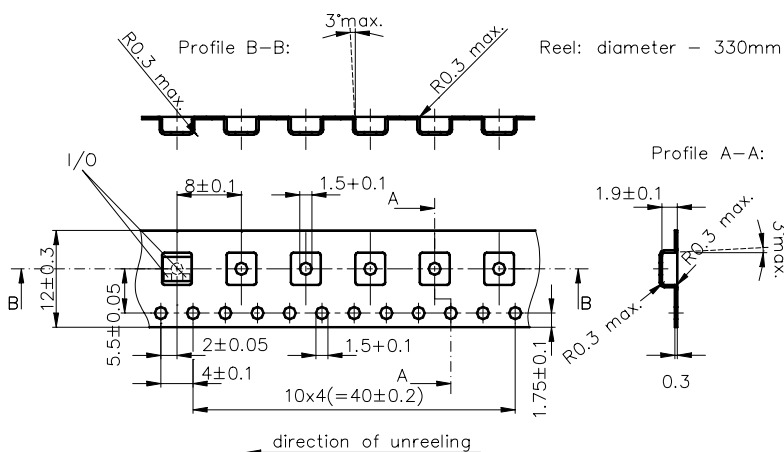
Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):

Delivery mode

- Blister tape acc. to IEC 286-3, grey
- Pieces/tape: 4000



© EPCOS AG 2001. All Rights Reserved. Reproduction, publication and dissemination of this data sheet, enclosures hereto and the information contained therein without EPCOS' prior express consent is prohibited.

The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

ISSUE DATE	20.05.03	ISSUE	P1	PUBLISHER	SAW MWC PD F	PAGE	4/4
------------	----------	-------	----	-----------	--------------	------	-----